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 TI Copper alloys for leads in semiconductor devices  
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AB The Cu alloys contain Fe 2-2.4, P 0.001-0.1, Zn 0.01-1, and Mg 0.001-0.1%. The Mg addn. improves heat resistance and strength without lowering elongation and elec. cond. The Cu alloys show good solderability. Thus, molten Cu alloy (contg. Fe 2.02, P 0.00188, Zn 0.012, and Mg 0.002%) was semicontinuously cast into an ingot slab 150 mm thick, and hot-rolled into a plate 11 mm thick. The trimmed plate was alternately cold rolled and annealed to manuf. a strip 0.25 mm thick, and then annealed for strain relief at 250-350.degree.. The strip showed tensile strength 52.1 kg/mm<sup>2</sup>, elongation 5%, elec. cond. 64% of IACS, and softening point 410.degree.. A solder coating showed good adhesion when the strip was bent after heating in air at 150.degree. for 500 h.

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